


Serial Number 	Application No. 10/616,827	Applicant(s) KUMAMOTO	

TERMINAL DISCLAIMER		<input checked="" type="checkbox"/> APPROVED		<input type="checkbox"/> DISAPPROVED	
The term of this patent shall not extend beyond the expiration date of U.S. Patent No:	6,632,704				
The term of this patent subsequent to the adjacent date has been disclaimed.					
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 PARALEGAL SPECIALIST
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**RESPONSE UNDER 37 C.F.R. § 1.116
-- EXPEDITED PROCEDURE --
EXAMINING GROUP 2800**

Our Docket No: 42P9482C

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
)
Takashi Kumamoto)
)
Application No: 10/616,827)
)
Filed: July 10, 2003)
)
For: Molded Flip Chip Package)
)

Examiner: Thai, Luan C.

Art Unit: 2827

**TERMINAL DISCLAIMER
APPROVED**

AUG 01 2004

**TECHNOLOGY CENTER 2800
SPECIAL PROGRAM CENTER**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

TERMINAL DISCLAIMER UNDER 37 C.F.R. § 1.321(c)

The undersigned attorney represents that the undersigned attorney is the attorney of record for the above-referenced patent application.

The assignee of the entire right, title, and interest in and to the above-referenced patent application is Intel Corporation ("assignee"), a Delaware corporation having a place of business at 2200 Mission College Boulevard, Santa Clara, California 95052.

FIRST CLASS CERTIFICATE OF MAILING

I hereby certify that I am causing the above-referenced correspondence to be deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and that this paper or fee has been addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA. 22313

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Signature

Date

Docket No. 42390P9482C
Application No. 10/616,827

The terminal part of any patent granted on the above-identified application that would extend beyond the expiration of the earlier of the full statutory term of

 X Patent Number 6,632,704, entitled Molded Flip Chip Package, and issued October 14, 2003,

is hereby disclaimed, except as provided below, and it is agreed that any patent so granted on the above-identified application shall be enforceable only for and during such period that the legal title to said patent shall be the same as the legal title to

 X Patent Number 6,632,704, entitled Molded Flip Chip Package, and issued October 14, 2003,

this agreement to run with any patent granted on the above-identified application and to be binding upon the grantor, its successors, or assigns.

No disclaimer is being made as to any terminal part of any patent granted on the above-identified application prior to the expiration of the full statutory term of

 X Patent Number 6,632,704, entitled Molded Flip Chip Package, and issued October 14, 2003,

in the event that it later expires for failure to pay a maintenance fee, is held unenforceable, is found invalid, is statutorily disclaimed in whole or terminally disclaimed under 37 C.F.R. § 1.321(a), has all claims canceled by a reexamination certificate, is reissued, or is otherwise terminated prior to expiration of its statutory term as presently shortened by any terminal disclaimer, except for the separation of legal title stated above.

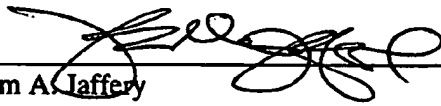
Enclosed is a check for \$ 110.00 for the fee under 37 C.F.R. § 1.20(d).

Please charge Deposit Account No. 02-2666 for any fee deficiency that may be due. A duplicate of the Fee Transmittal is enclosed for Deposit Account charging purposes.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Dated: 7/14/04


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